

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

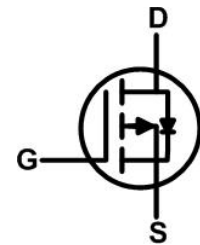
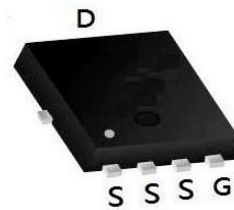
**Product Summary**


BVDSS	R <sub>DS(on)</sub>	I <sub>D</sub>
-20V	6mΩ	-60A

**Description**

The XXW60P02D is the high cell density trench P-ch MOSFETs, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the synchronous buck converter applications.

The XXW60P02D meet the RoHS and Green Product requirement with full function reliability approved.

**PDFN3333-8L Pin Configuration**

**Absolute Maximum Ratings (T<sub>A</sub> = 25°C, unless otherwise noted)**

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	-20	V
Gate-Source Voltage		V <sub>GS</sub>	±10	V
Continuous Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	-60	A
	T <sub>C</sub> =100°C		-34.8	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	-220	A
Single Pulse Avalanche Energy <sup>2</sup>		E <sub>AS</sub>	61.25	mJ
Total Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	39	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

**Thermal Characteristics**

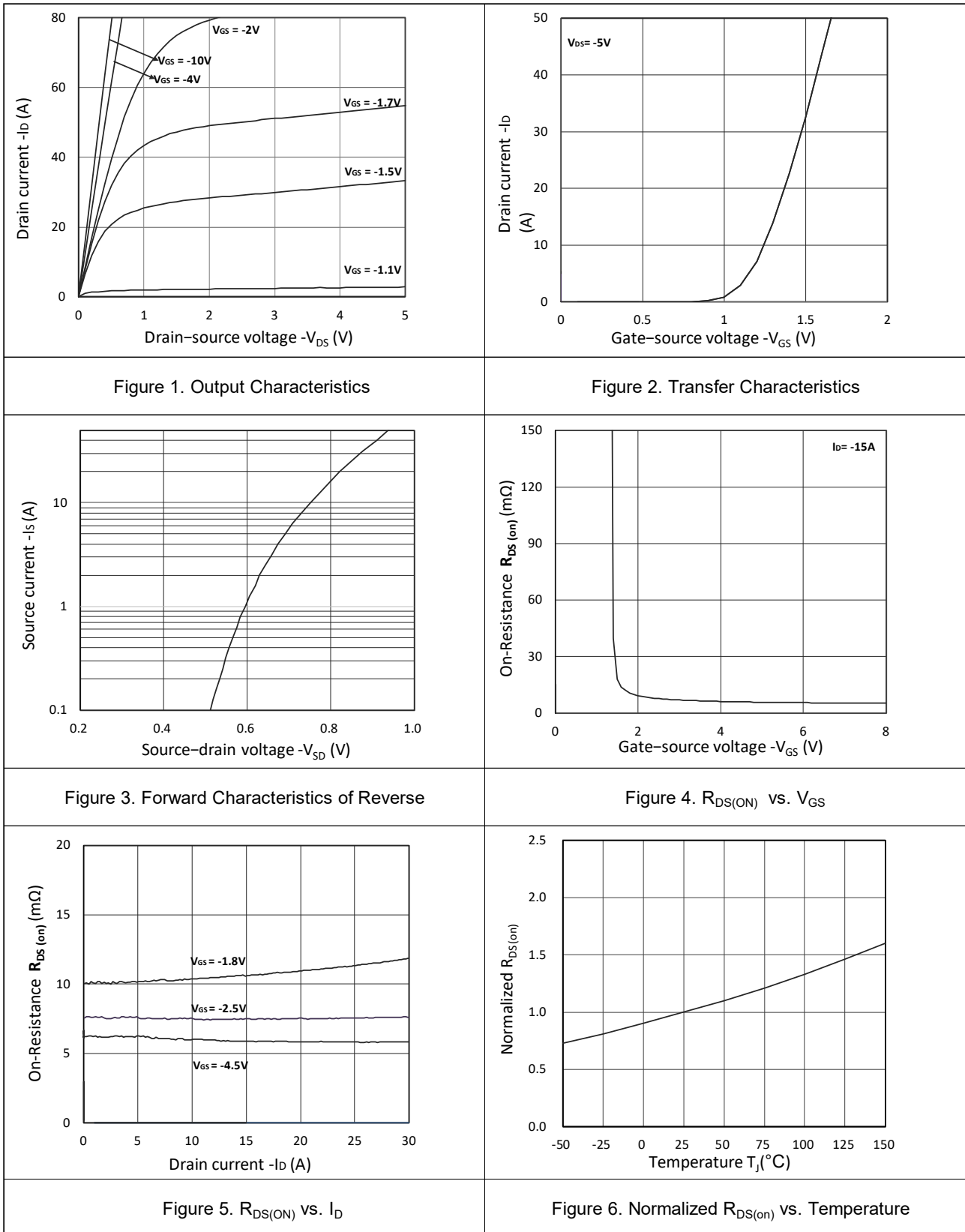
Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	R <sub>θJA</sub>	38	°C/W
Thermal Resistance from Junction-to-Case	R <sub>θJC</sub>	3.2	°C/W

**Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	<b>V<sub>(BR)DSS</sub></b>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20	-	-	V	
Gate-body Leakage current	<b>I<sub>GSS</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±10V	-	-	±100	nA	
Zero Gate Voltage Drain Current	<b>I<sub>DSS</sub></b>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	T <sub>J</sub> =25°C	-	-	-1	μA
			T <sub>J</sub> =100°C	-	-	-100	
Gate-Threshold Voltage	<b>V<sub>GS(th)</sub></b>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-	-1.0	V	
Drain-Source on-Resistance <sup>4</sup>	<b>R<sub>DS(on)</sub></b>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -15A	-	6	8.2	mΩ	
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -10A	-	7.5	10		
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -8A	-	10.2	15		
Forward Transconductance <sup>4</sup>	<b>g<sub>fs</sub></b>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -15A	-	78	-	S	
<b>Dynamic Characteristics<sup>5</sup></b>							
Input Capacitance	<b>C<sub>iss</sub></b>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz	-	3560	-	pF	
Output Capacitance	<b>C<sub>oss</sub></b>		-	500	-		
Reverse Transfer Capacitance	<b>C<sub>rss</sub></b>		-	430	-		
Gate Resistance	<b>R<sub>g</sub></b>	f = 1MHz	-	11	-	Ω	
<b>Switching Characteristics<sup>5</sup></b>							
Total Gate Charge	<b>Q<sub>g</sub></b>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -15A	-	43	-	nC	
Gate-Source Charge	<b>Q<sub>gs</sub></b>		-	7.9	-		
Gate-Drain Charge	<b>Q<sub>gd</sub></b>		-	11.2	-		
Turn-on Delay Time	<b>t<sub>d(on)</sub></b>	V <sub>GS</sub> = -4.5V, V <sub>DD</sub> = -10V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = -15A,	-	14.5	-	ns	
Rise Time	<b>t<sub>r</sub></b>		-	20.2	-		
Turn-off Delay Time	<b>t<sub>d(off)</sub></b>		-	93	-		
Fall Time	<b>t<sub>f</sub></b>		-	161	-		
Body Diode Reverse Recovery Time	<b>t<sub>rr</sub></b>	I <sub>F</sub> = -15A, dI <sub>F</sub> /dt = 100A/μs	-	28	-	ns	
Body Diode Reverse Recovery Charge	<b>Q<sub>rr</sub></b>		-	25.7	-	nC	
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>4</sup>	<b>V<sub>SD</sub></b>	I <sub>S</sub> = -1A, V <sub>GS</sub> = 0V	-	-	-1.2	V	
Continuous Source Current	<b>I<sub>S</sub></b>	T <sub>C</sub> =25°C	-	-	-60	A	

**Notes:**

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.
2. The EAS data shows Max. rating . The test condition is V<sub>DD</sub>= -25V, V<sub>GS</sub>= -10V, L= 0.1mH, I<sub>AS</sub>= 35A.
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

**Typical Characteristics**


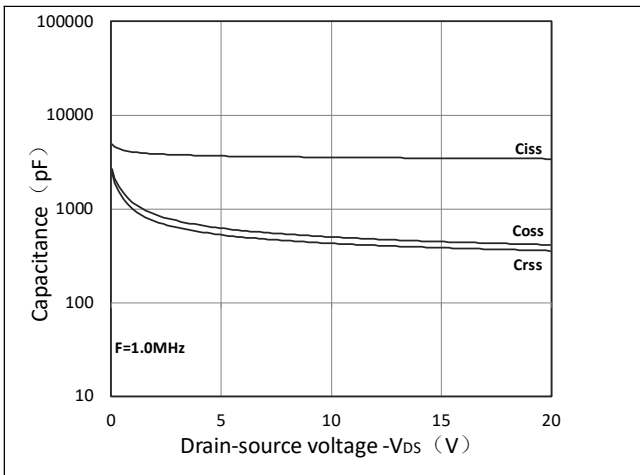


Figure 7. Capacitance Characteristics

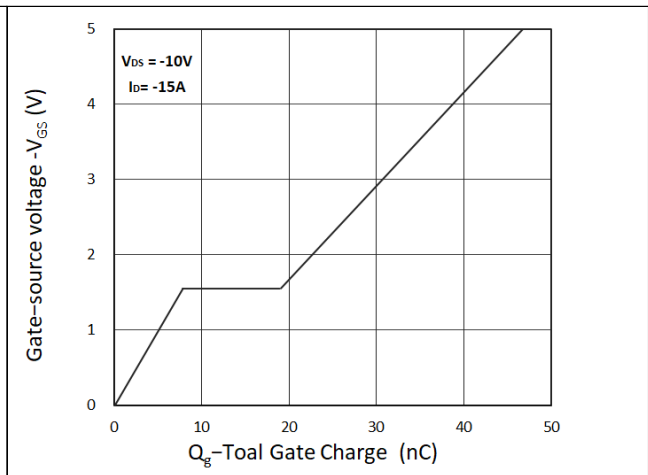


Figure 8. Gate Charge Characteristics

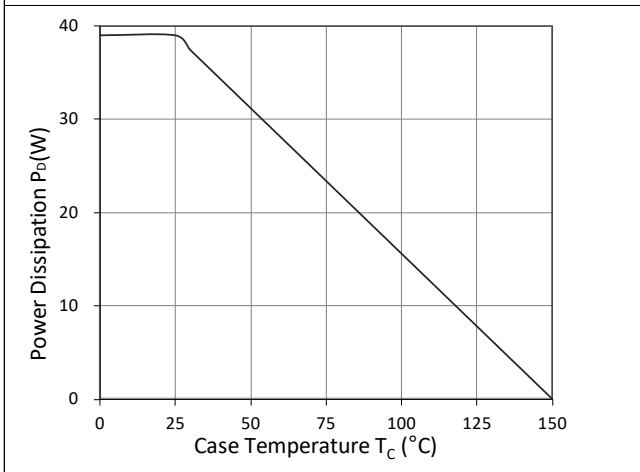


Figure 9. Power Dissipation

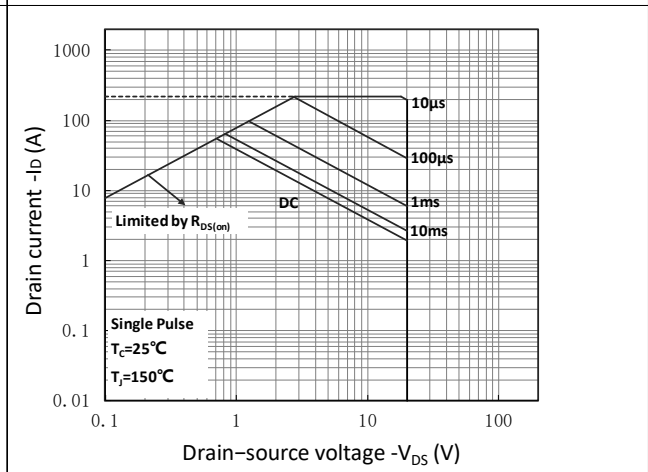


Figure 10. Safe Operating Area

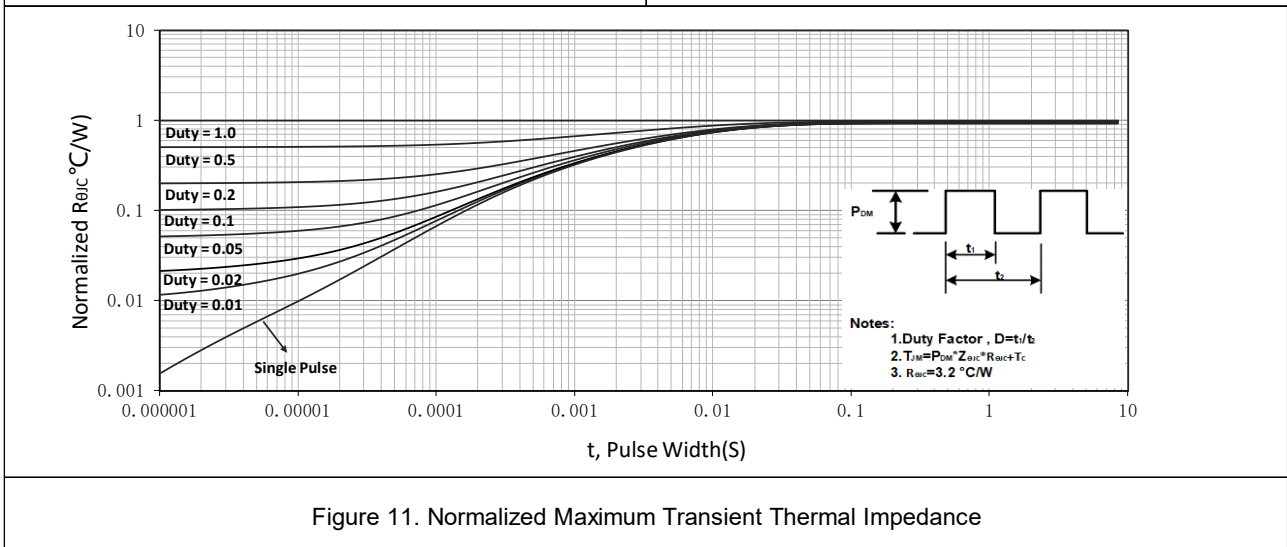
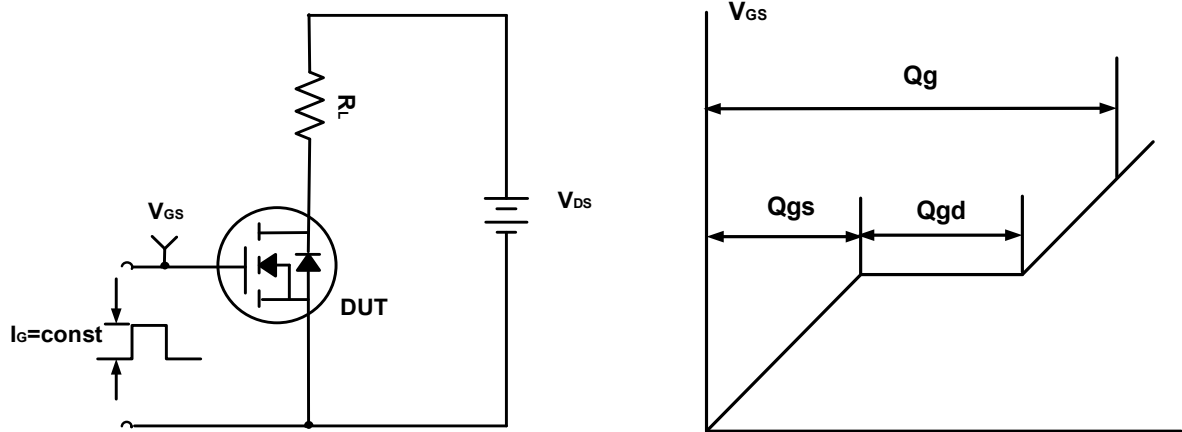
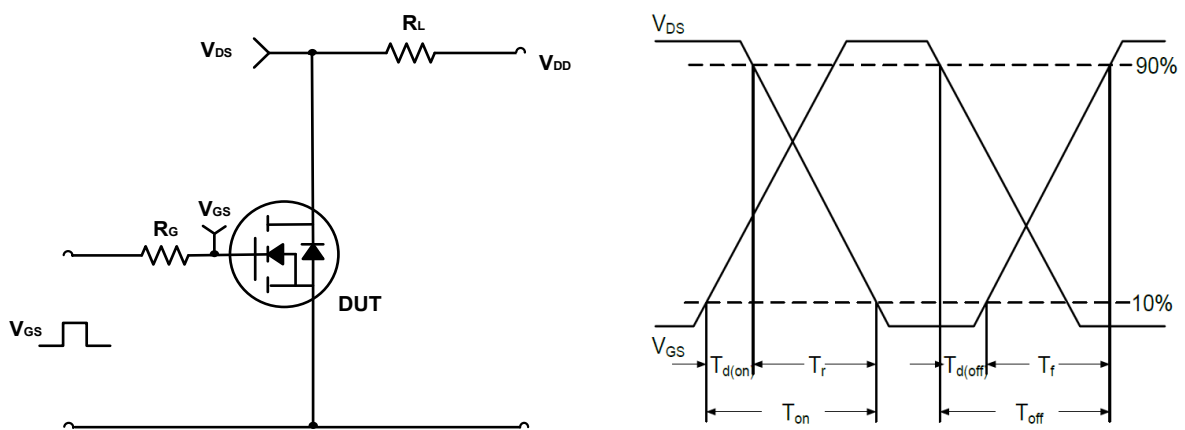


Figure 11. Normalized Maximum Transient Thermal Impedance

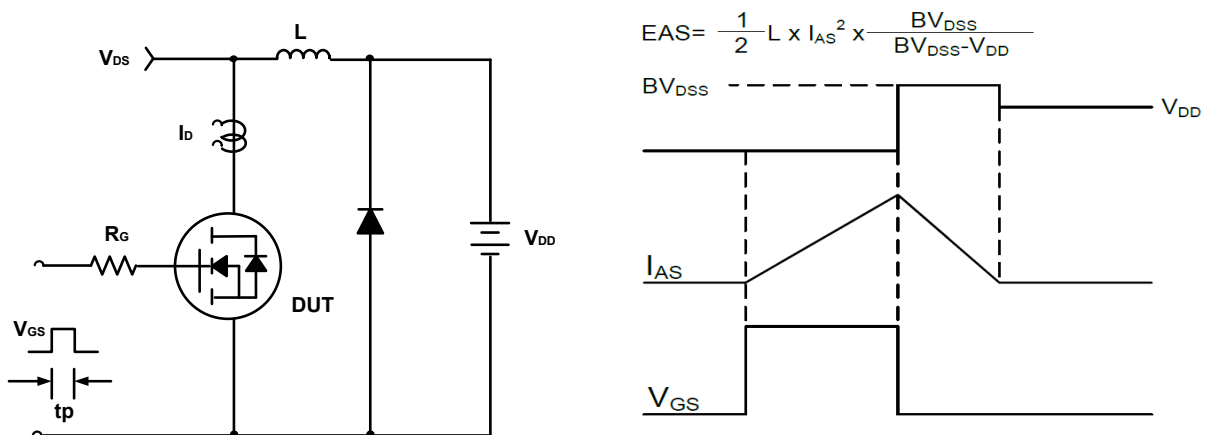
**Test Circuit**



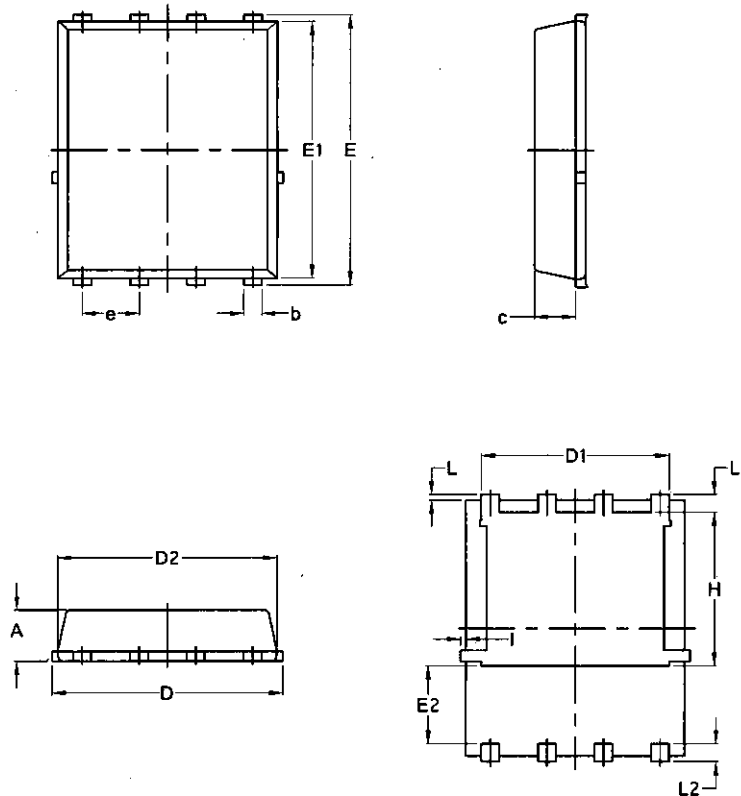
**Figure A. Gate Charge Test Circuit & Waveforms**



**Figure B. Switching Test Circuit & Waveforms**



**Figure C. Unclamped Inductive Switching Circuit & Waveforms**

**Package Mechanical Data-PDFN3333-8L-Single**

**COMMON DIMENSIONS**

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		